

CX3HGSM AT CRYSTAL

9.6 MHz to 250 MHz

High Shock, Low Profile, Miniature Surface Mount AT Quartz Crystal

Fundamental Mode: 9.6 MHz - 250 MHz

DESCRIPTION

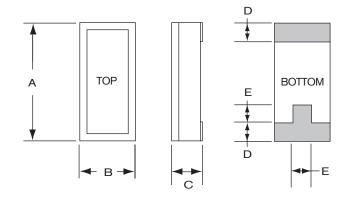
STATEK's miniature CX3SM AT crystals in leadless ceramic packages are designed for surface mounting on printed circuit boards or hybrid substrates. These crystals are low profile and have a small land pattern. These rugged crystals are designed for applications requiring higher shock and vibration survival.

FEATURES

- High shock and vibration survival
- Designed for surface mount applications using infrared, vapor phase, or epoxy mount techniques.
- Low profile (less than 1.5 mm available) hermetically sealed ceramic package
- Excellent aging characteristics
- Available with glass or ceramic lid
- High shock and vibration resistance
- Custom designs available
- Full military testing available
- Designed and manufactured in the USA

actual size side view glass lid ceramic lid

PACKAGE DIMENSIONS



APPLICATIONS

Medical

Monitoring Equipment

Industrial, Computer & Communications

- Instrumentation
- Down-hole Data Recorder
- Engine Control
- Handheld Inventory Control
- Telemetry

Military & Aerospace

- Communications
- Smart Munitions
- Timing Devices
- Surveillance Devices

	TYPICAL		MAXI	MUM	
DIM	inches	mm	inches	mm	
Α	0.263	6.68	0.270	6.86	
В	0.097	2.46	0.104	2.64	
С	-	-	see	see below	
D	0.052	1.32	0.058	1.47	
Е	0.030	0.76	0.035	0.89	

B 4 B 3/1B 41 1B 4

THICKNESS (DIM C) MAXIMUM

	GLASS LID		CERAMIC L	JD
	inches	mm	inches	mm
SM1	0.053	1.35	0.067	1.70
SM2/SM4	0.055	1.40	0.069	1.75
SM3/SM5	0.058	1.47	0.072	1.83

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SPECIFICATIONS

Specifications are typical at 25°C unless otherwise noted. Specifications are subject to change without notice.

Fundamental Frequency	<u>10 MHz</u>	<u>32 MHz</u>	<u>155.52 MHz</u>
Motional Resistance $R_1(\Omega)$	60	25	10
Motional Capacitance $C_1(fF)$	2.8	6.2	4.0
Quality Factor Q (k)	95	30	30
Shunt Capacitance C ₀ (pF)	1.4	2.3	2.3

Calibration Tolerances¹ ± 100 ppm, or tighter as required

Load Capacitance² 20 pF for f ≤ 50 MHz

10 pF for f > 50 MHz

Drive Level 500 μ W MAX for f \leq 50 MHz

200 μW MAX for f > 50 MHz

Frequency-Temperature

Stability^{1,3}

 \pm 50 ppm to \pm 10 ppm (Commercial) \pm 100 ppm to \pm 20 ppm (Industrial)

 \pm 100 ppm to \pm 30 ppm (Military)

Aging, first year⁴ 10 ppm MAX

Shock, survival Up to 20,000 g, 0.3 ms, 1/2 sine

Vibration, survival⁵ 20 g, 10-2,000 Hz swept sine

Operating Temp. Range -10°C to +70°C (Commercial)

 -40° C to $+85^{\circ}$ C (Industrial) -55°C to $+125^{\circ}$ C (Military)

Storage Temp. Range -55°C to +125°C

Max Process Temperature 260°C for 20 sec.

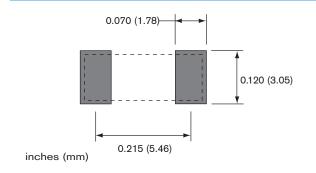
- 1. Other tolerances available. Contact factory.
- 2. Unless specified otherwise.
- Does not include calibration tolerance. The characteristics of the frequency stability over temperature follow that of the AT thickness-shear mode.
- 10 ppm MAX for frequencies below 40 MHz. For tighter tolerances and higher frequencies contact factory.
- 5. Per MIL-STD-202G, Method 204D, Condition D. Random vibration testing also available.

TERMINATIONS

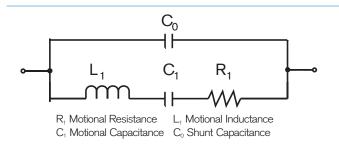
<u>Designation</u>	<u>Termination</u>
SM1	Gold Plated
SM2	Solder Plated
SM3	Solder Dipped
SM4	Solder Plated (Lead Free)
SM5	Solder Dipped (Lead Free)

Max Process Temperature 260°C for 20 sec.

SUGGESTED LAND PATTERN



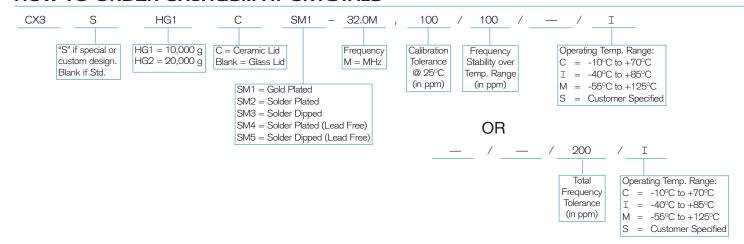
EQUIVALENT CIRCUIT



PACKAGING OPTIONS

- Tray Pack
- 16mm tape, 7" or 13" reels
 Per EIA 481 (see Tape and Reel data sheet 10109)

HOW TO ORDER CX3HGSM AT CRYSTALS



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